

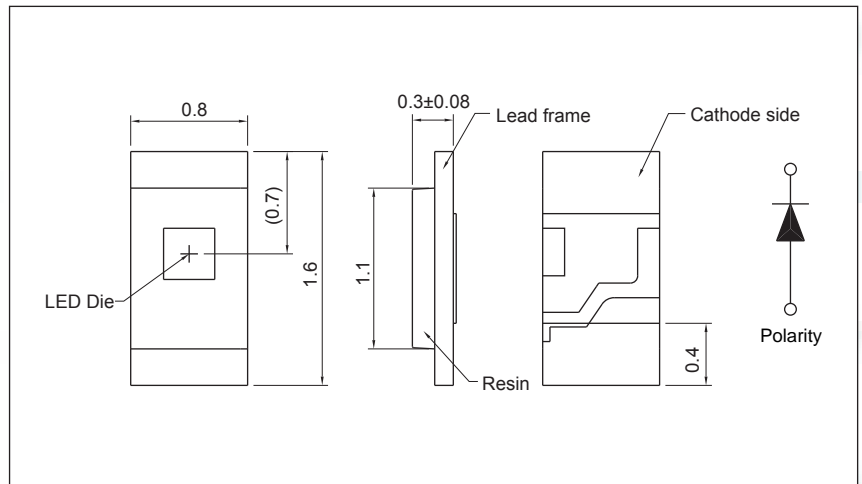
Features

- Chip LED (1.6x0.8x0.3)
- Super compact

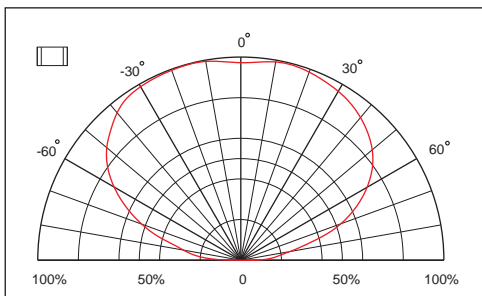
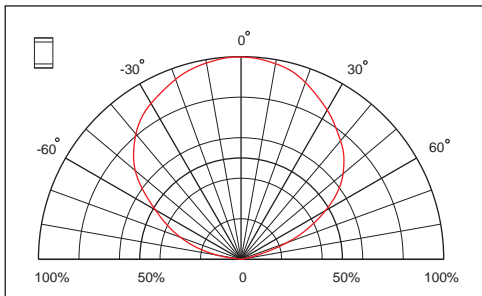


Package Outline Dimensions

(Unit: mm Tolerance: +/-0.1)

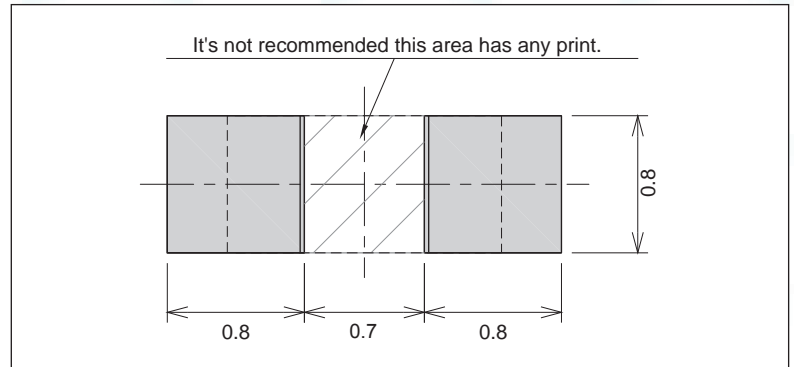


Directive Characteristics



Recommended Soldering Pattern

(Unit:mm)



Absolute Maximum Ratings

(Ta=25°C)

Item	Symbol	AllnGaP	InGaN	Unit
Power Dissipation	P _D	72	117	mW
DC Forward Current	I _F	30	30	mA
Pulsed Forward Current	I _{FP} *	100	120	mA
Reverse Voltage	V _R	5		V
Operating Temperature	T _{OP}	-30 to 80		°C
Storage Temperature	T _{ST}	-40 to 85		°C

* 0.1msec pulse, 10% duty cycle.

Electrical / Optical Characteristics

(Ta=25°C)

Part Number	Emitting color	Material	Forward Voltage(V _F)		Wavelength (nm) typ.			Luminous Intensity (mcd)*		I _F (mA)	Viewing Angle 2θ _{1/2}
			typ.	max.	D	P	Δ	min.	typ.		
HT-F199UYG5	Ultra Bright Yellow Green	AllnGaP	1.8	2.0	573	574	20	18	28	5	x=140 y=120
HT-F199USD5	Ultra Bright Orange	AllnGaP	1.8	2.0	622	636	17	18	28	5	x=140 y=120
HT-F199NB5	Blue	InGaN	2.8	3.15	470	468	40	18	28	5	x=140 y=120
HT-F199NG5	Green	InGaN	2.8	3.15	527	520	40	50	70	5	x=140 y=120
HT-F199TW5	White	InGaN	2.8	3.15	x=0.29 y=0.31	-	-	40	50	5	x=140 y=120

*Per NIST standards

